TI0249-D3572, JUNE 1990

- Packaged in Shrink Small-Outline 300-mil Packages (SSOP) and 380-mil Fine-Pitch Ceramic Flat Packages Using 25-mil Center-to-Center Pin Spacings
- Inputs are TTL- or CMOS-Voltage Compatible
- 3-State Outputs Drive Bus Lines Directly
- Flow-Through Architecture Optimizes PCB Layout
- Distributed V<sub>CC</sub> and GND Pin Configuration Minimizes High-Speed Switching Noise
- EPIC™ (Enhanced-Performance Implanted CMOS) 1-µm Process
- 500-mA Typical Latch-Up Immunity at 125°C

## description

The 'AC16473 and 'ACT16473 are inverting 18-bit latched bus transceivers composed of two 9-bit sections with separate control signals. For either 9-bit transceiver section, data flow in the A-to-B mode is controlled by output enable (1OEAB or 2OEAB) and latch enable (1LEAB or 2LEAB) inputs. When 1OEAB (or 2OEAB) is low, the corresponding B outputs are active (high or low logic levels). When 10EAB (or 20EAB) is high, the corresponding B outputs are in the high-impedance state. The latches retain their prior states when 1LEAB (or 2LEAB) is high and reflect the states of the corresponding A inputs when 1LEAB (or 2LEAB) is low.

## 54AC16473, 54ACT16473 ... WD PACKAGE 74AC16473, 74ACT16473 ... DL PACKAGE (TOP VIEW) 10FAR DI VISADIOFRA

10EAB [	1	<b>₩</b> 56	∐10EBA
1 LEAB	2	55	1 LEBA
1A1	3	54	]1B1
GND [	]₄	53	GND
1A2 [	]5	52	] 1B2
1A3 [	6	51	] 1B3
V <sub>CC</sub> [	17	50	□ V <sub>CC</sub>
1A4	]8	49	] 1B4
1A5 [	]9	48	] 1 <b>B</b> 5
1A6 [	10	47	] 1B6
GND [	<b>]</b> 11	46	GND
1A7 [	12	45	] 187
1A8 [	13	44	]1B8
1A9 [	14	43	] 1 B9
2A1[	15	42	□ 2B1
2A2 [	16	41	] 2B2
2A3 [	]17	40	_ 2B3
GND [	18	39	GND
2A4 [	]19	38	<b>284</b>
2A5 [	20	37	285
2 <b>A</b> 6 [	21	36	286
V <sub>cc</sub> [	22	35	□v <sub>cc</sub>
2A7 [	23	34	287
2A8 [	24	33	] 2B8
GND [	25	32	GND
2A9 [	]26	31	☐ 2B9
2LEAB [	27	30	2LEBA
20EAB	]28	29	20EBA

## **FUNCTION TABLE, EACH SECTION<sup>†</sup>**

INP	UTS		B OUTPUTS	
LEAB	OEAB	LATCH DATA		
L	L	Current A Data	Inverse of Current A Data	
H	L	Previous A Data	Inverse of Previous A Data	
L	Н	Current A Data	Z	
H	H	Previous A Data	Z	

<sup>&</sup>lt;sup>†</sup> A-to-B data flow is shown. B-to-A data flow is controlled analogously by OEBA and LEBA.

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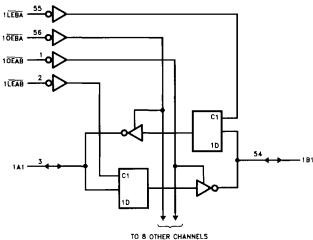
Data flow from B to A is similar, but uses 10EBA and/or 20EBA and 1LEBA and/or 2LEBA.

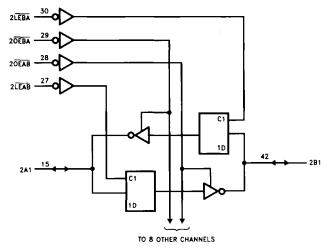
The 74AC16473 and 74ACT16473 are packaged in TI's shrink small-outline package (SSOP) with 25-mil center-to-center pin spacings. This package provides twice the I/O pin count and functionality of a standard small-outline package in the same printed-circuit-board area.

The 'AC16473 has CMOS-compatible input thresholds. The 'ACT16473 has TTL-compatible input thresholds.

The 54AC16473 and 54ACT16473 are characterized over the full military temperature range of -55°C to 125°C. The 74AC16473 and 74ACT16473 are characterized for operation from -40°C to 85°C.

## logic diagram (positive logic)







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